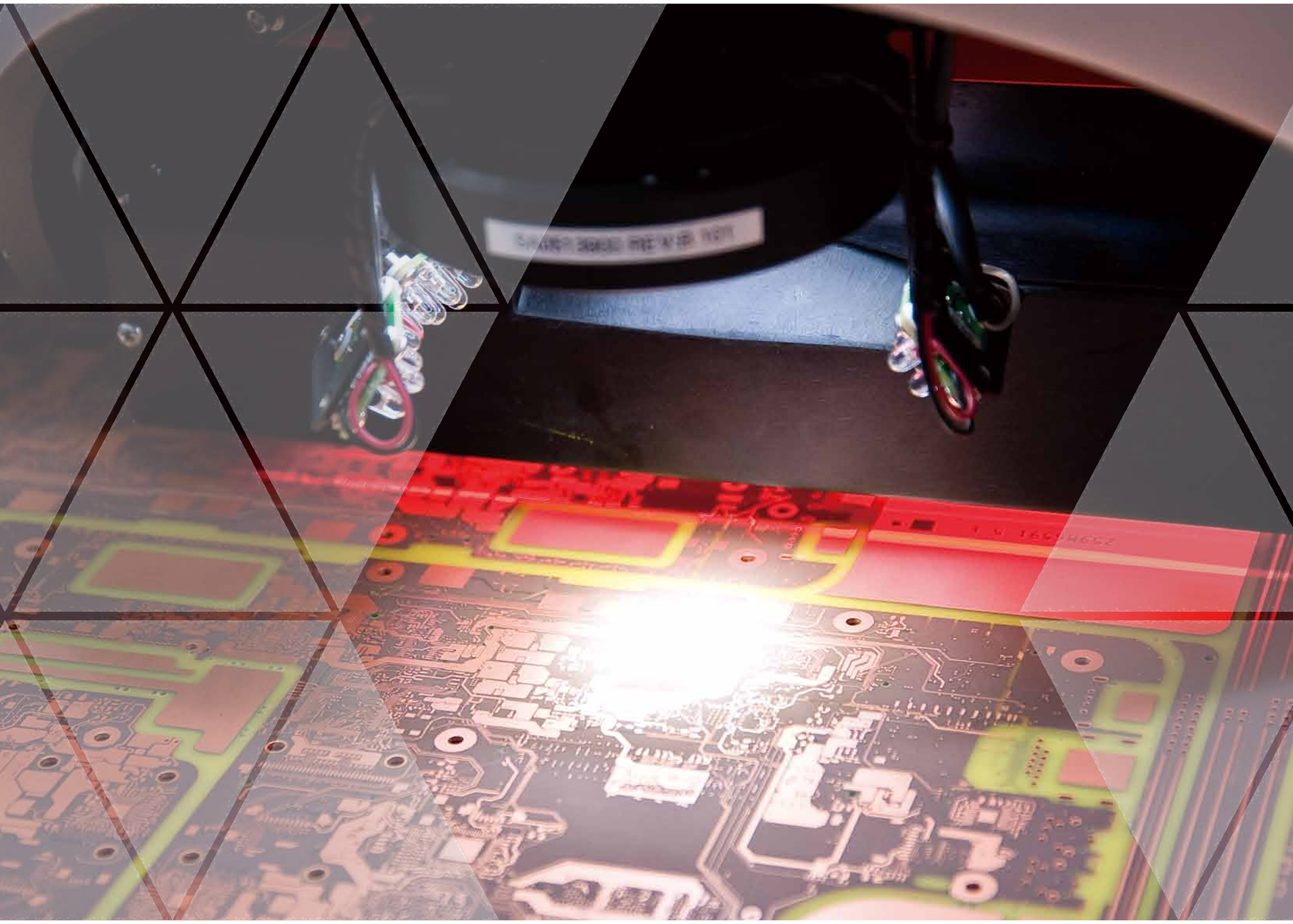
Phoenix Inspectify



CIMS
By Camtek technology

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Phoenix Inspectify

PCB technology	Down to 30µm line/space
Throughput	Up to 200 sides/hour, 18" × 24" (457mm × 610mm)
Panel Size (maximum)	30" × 24" (762mm × 610mm)
Panel Thickness Range	1mil - 200mil (0.025mm - 5mm)
Panel Types and Designs	Inner and outer layers, build-up and sequential lamination layers including Signal, Mix and P&G, Cross-Shield, Laser drilled layers
Materials Inspected	All copper foil types; Copper plating; Photo-resist (optional); Gold plating; Teflon and Ceramics (optional); Silver-Halide and Diazo, Alternative Oxide-Durabond
Detectable Defect Types	Open and Short-circuit, Nick, Mouse-bite, Protrusion, Pinhole, Island, Dish-down, Line/Space width violations, Annular ring violations, Extra and Missing features
Reference Source Data	CAM
Tooling	Pin-less
Operating System	Windows 7™ 64bit
Detection and set-up engine	Powered by Spark™
Verification and Repair Methods	Inspectify™; Offline verification station
Dimensions	Height – 65.7" (167cm) Width – 70.0" (178cm) Depth – 66.5" (169cm) Weight – 850Kg Power – 200±10%VAC; 50/60Hz; 2.5Kw
Compressed Air	6ATM, 1L/min
Temperature and Humidity	22±3°C; 50±10%RH

Optional Features	Fi – final inspection option for finished boards +2CD – 2D measurement of circuit elements LDI – laser drill inspection option CDB/CDBIC – defects classification and virtual defects mapping

Powered by SPARK 2.0

Powered by Microlight

Powered by Spark™

- Superior detection
- Lowest false calls rate
- Simple and quick setup
- Fast adaptation cycle

Powered by Microlight™

Advanced illumination technology provides:

- Flexible light coverage to detect fine shorts and dishdowns
- A full spectrum of waves' length suitable to all type of materials
- Adaptability for special applications